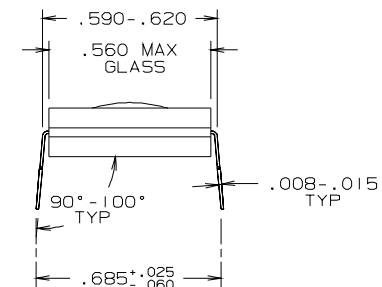
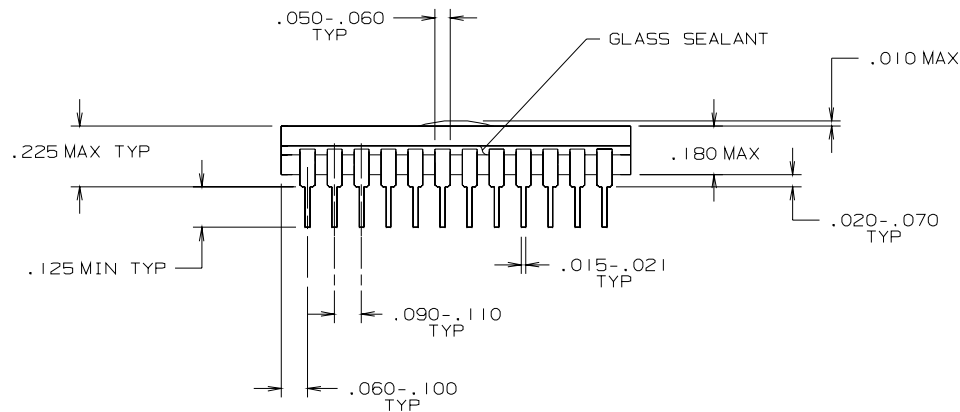
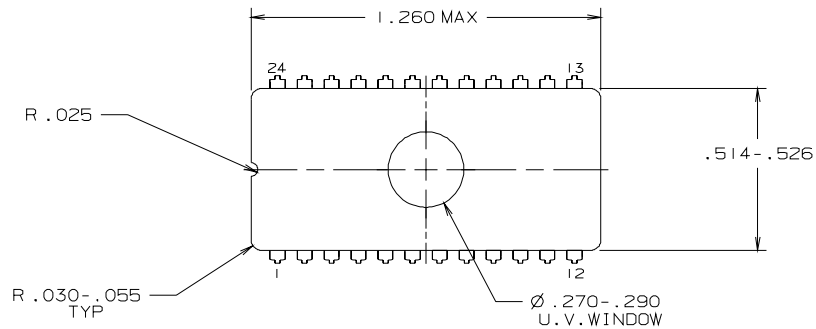


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
G	REVISE AND REDRAW	09001	01/08/92	DEG/



MIL/AERO CONFIGURATION CONTROL

NOTES: UNLESS OTHERWISE SPECIFIED

- LEAD FINISH TO BE ONE OF THE FOLLOWING:
 - 200 MICROINCHES MINIMUM SOLDER MEASURED AT THE CREST OF THE MAJOR FLATS.
 - 200-800 MICROINCHES TIN PLATE OVER 50-300 MICROINCHES NICKEL UNDERPLATE OR BASIS METAL.
 - 50-100 MICROINCHES GOLD OVER 50-350 MICROINCHES NICKEL UNDERPLATE.
- LEAD FINISH, NICKEL UNDERPLATE AND BASIS METAL SHALL CONFORM TO THE REQUIREMENTS OF MIL-M-38510.
- NO JEDEC REGISTRATION AS OF 12/16/91.

APPROVALS	DATE	NATIONAL SEMICONDUCTOR CORPORATION		
DRAWN	D.E. GRADY	01/08/92	2900 Semiconductor Drive, Santa Clara, CA 95052-8090	
DFTG. CHK.			CERDIP (JQ),	
ENGR. CHK.			24 LEAD, EPROM,	
APPROVAL			SMALL WINDOW	
PROJECTION		SCALE	SIZE	DRAWING NUMBER
INCH		N/A	C	MKT-J24AQ
		FORMERLY:	N/A	SHEET 1 OF 1